



SMD Auto COG HV Flex, Ceramic, 330 pF, 10%, 3,000 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, Automotive Grade, 1812, 2.3 mm



General Information	
Series	SMD Auto COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra- Stable, Automotive Grade
Features	FT-CAP, Ultra-Stable, Automotive Grade
RoHS	Yes
Termination	Flexible Termination
Marking	No
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	87 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	2.5mm +/-0.20mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

Specifications	
Capacitance	330 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3,600 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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